


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT																												
<p>Application Number: 09/779123 </p> <p>Confirmation Number: 9269</p> <p>First Named Applicant: Anantha Sethuraman</p> <p>Attorney Docket Number: 5298-02502</p> <p>Art Unit: 2823</p> <p>Examiner: Hsien-Ming Lee</p> <p>Search string: (5958794 or 5972124).pn.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td><i>Lee</i></td><td>1</td><td>5958794</td><td>1999-09-28</td><td>Bruxvoort et al.</td><td></td><td></td><td></td></tr><tr><td><i>Lee</i></td><td>2</td><td>5972124</td><td>1999-10-26</td><td>Sethuraman et al.</td><td></td><td></td><td></td></tr></tbody></table> <p>Signature</p> <table border="1"><thead><tr><th>Examiner Name</th><th>Date</th></tr></thead><tbody><tr><td><i>Hsien Ming Lee</i></td><td><i>4/20/04</i></td></tr></tbody></table>		init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass	<i>Lee</i>	1	5958794	1999-09-28	Bruxvoort et al.				<i>Lee</i>	2	5972124	1999-10-26	Sethuraman et al.				Examiner Name	Date	<i>Hsien Ming Lee</i>	<i>4/20/04</i>
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